SDFS019B - JANUARY 1989 - REVISED JANUARY 1997

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

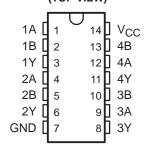
A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54F86 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F86 is characterized for operation from 0°C to 70°C.

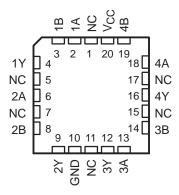
FUNCTION TABLE (each gate)

| INP | UTS | OUTPUT |
|-----|-----|--------|
| Α | В | Y |
| L | L | L |
| L | Н | н |
| Н | L | н |
| Н | Н | L |

SN54F86...J PACKAGE SN74F86...D OR N PACKAGE (TOP VIEW)

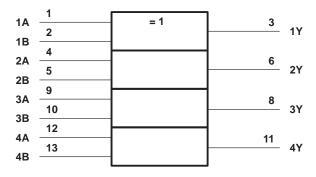


SN54F86 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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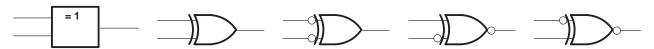


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exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

EXCLUSIVE OR



These are five equivalent exclusive-OR symbols valid for an 'F86 gate in positive logic; negation may be shown at any two ports.

The output is active (low) if all inputs stand at the same logic level (i.e., A = B). EVEN-PARITY ELEMENT ODD-PARITY ELEMENT The output is active (low) if an even number of inputs (i.e., o or 2) are active. The output is active (high) if an odd number of outputs (i.e., only 1 of the 2) are active.

| absolute maximum rating | as over operatin | a free-air temp | erature range (| (unless otherwise noted)† |
|-------------------------|------------------|-------------------------------------|---|---------------------------|
| | , | g • • • • • • • • • • • • • • • • • | , | () |

| | <u> </u> |
|--|--------------------------|
| Supply voltage range, V _{CC} | 0.5 V to 7 V |
| Input voltage range, V _I (see Note 1) | –1.2 V to 7 V |
| Input current range | |
| Voltage range applied to any output in the high state | 0.5 V to V _{CC} |
| Current into any output in the low state | 40 mA |
| Package thermal impedance, θ_{JA} (see Note 2): D package | 127°C/W |
| N package | |
| Storage temperature range, T _{stg} | –65°C to 150°C |
| | |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

| | | SN54F86 | | | 5 | UNIT | | |
|-----------------|--------------------------------|---------|-----|-----|-----|------|-----|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | | 2 | | | V |
| VIL | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| lik | Input clamp current | | | -18 | | | -18 | mA |
| loh | High-level output current | | | -1 | | | -1 | mA |
| l _{OL} | Low-level output current | | | 20 | | | 20 | mA |
| T _A | Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |



NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | Ι , | TEST CONDITIONS | | | | 5 | N74F86 | | UNIT |
|------------------|----------------------------|--------------------------|-----|-----|-------|-----|--------|-------|------|
| PARAMETER | ' | MIN | TYP | MAX | MIN | TYP | MAX | UNII | |
| VIK | $V_{CC} = 4.5 \text{ V},$ | $I_{I} = -18 \text{ mA}$ | | | -1.2 | | | -1.2 | V |
| Va.: | $V_{CC} = 4.5 \text{ V},$ | $I_{OH} = -1 \text{ mA}$ | 2.5 | 3.4 | | 2.5 | 3.4 | | V |
| VOH | $V_{CC} = 4.75 \text{ V},$ | $I_{OH} = -1 \text{ mA}$ | | | | 2.7 | | | V |
| V _{OL} | $V_{CC} = 4.5 \text{ V},$ | $I_{OL} = 20 \text{ mA}$ | | 0.3 | 0.5 | | 0.3 | 0.5 | V |
| lį | $V_{CC} = 5.5 \text{ V},$ | V _I = 7 V | | | 0.1 | | | 0.1 | mA |
| lіН | $V_{CC} = 5.5 \text{ V},$ | V _I = 2.7 V | | | 20 | | | 20 | μΑ |
| I _Ι Γ | $V_{CC} = 5.5 \text{ V},$ | V _I = 0.5 V | | | - 0.6 | | | - 0.6 | mA |
| los [‡] | $V_{CC} = 5.5 \text{ V},$ | V _O = 0 | -60 | | -150 | -60 | | -150 | mA |
| ІССН | $V_{CC} = 5.5 \text{ V},$ | See Note 3 | | 15 | 23 | | 15 | 23 | mA |
| ICCL | $V_{CC} = 5.5 \text{ V},$ | V _I = 4.5 V | | 18 | 28 | | 18 | 28 | mA |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | C _I R _I | CC = 5 V L = 50 pl L = 500 s A = 25°C | F, Ω , | V _C C _L R _L T _A | UNIT | | | |
|------------------|---------------------------|--------------------|----------------------------------|--|-------------------------|--|------|---------|-----|-----|
| | | | ′F86 | | | SN54F86 | | SN74F86 | | |
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | A or B | V | 3 | 4 | 5.5 | 3 | 7 | 3 | 6.5 | |
| t _{PHL} | (other input low) | ī | 3 | 4.2 | 5.5 | 2.6 | 8 | 3 | 6.5 | ns |
| t _{PLH} | A or B (other input high) | V | 3.5 | 5.3 | 7 | 3.5 | 10 | 3.5 | 8 | ns |
| t _{PHL} | | (other input high) | · | 3 | 4.7 | 6.5 | 3 | 8 | 3 | 7.5 |

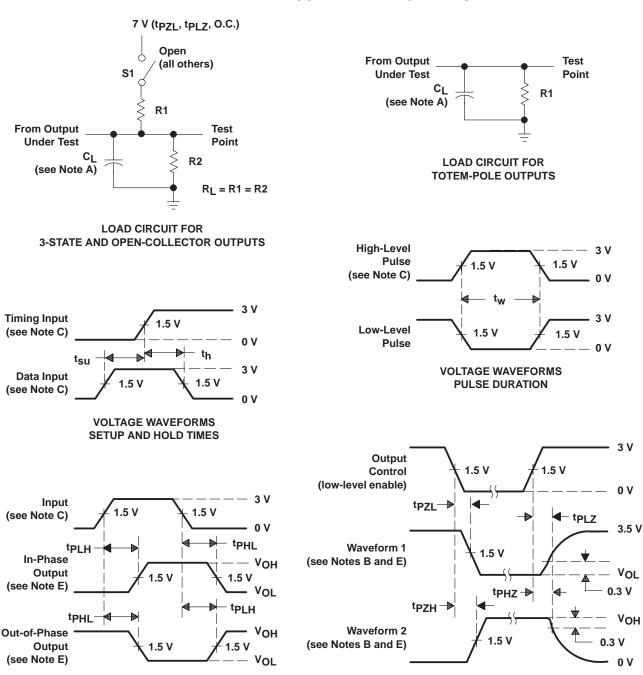
[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 3: I_{CCH} is measured with outputs open, and the A or B input (not both) at 4.5 V. Remaining inputs are grounded.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES (see Note D)

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $t_r = t_f \le 2.5 \text{ ns}$, duty cycle = 50%.

VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

| Orderable part number | Status | Material type | Package Pins | Package qty Carrier | RoHS | Lead finish/ Ball material | MSL rating/ Peak reflow | Op temp (°C) | Part marking |
|-----------------------|----------|---------------|----------------|-----------------------|------|-------------------------------|----------------------------|--------------|--------------|
| | (1) | (2) | | | (3) | (4) | (5) | | (6) |
| SN74F86D | Obsolete | Production | SOIC (D) 14 | - | - | Call TI | Call TI | 0 to 70 | F86 |
| SN74F86DR | Active | Production | SOIC (D) 14 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F86 |
| SN74F86DR.A | Active | Production | SOIC (D) 14 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F86 |
| SN74F86DRG4 | Active | Production | SOIC (D) 14 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F86 |
| SN74F86N | Active | Production | PDIP (N) 14 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74F86N |
| SN74F86N.A | Active | Production | PDIP (N) 14 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74F86N |
| SN74F86NE4 | Active | Production | PDIP (N) 14 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74F86N |
| SN74F86NSR | Active | Production | SOP (NS) 14 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74F86 |
| SN74F86NSR.A | Active | Production | SOP (NS) 14 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74F86 |
| SN74F86NSR.B | Active | Production | SOP (NS) 14 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74F86 |

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN74F86DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74F86NSR | SOP | NS | 14 | 2000 | 330.0 | 16.4 | 8.45 | 10.55 | 2.5 | 12.0 | 16.2 | Q1 |

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74F86DR | SOIC | D | 14 | 2500 | 353.0 | 353.0 | 32.0 |
| SN74F86NSR | SOP | NS | 14 | 2000 | 353.0 | 353.0 | 32.0 |

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN74F86N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F86N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F86N.A | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F86N.A | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F86NE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F86NE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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